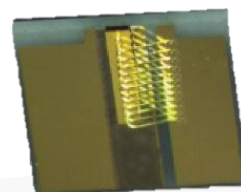


High Power RSOA Chip on Carriers



Part Number: COC-286

High Power RSOA Chip on Carrier
Single-Mode RSOA Curved Waveguide
Wavelength at 1550nm



Features

- High Output Power
- High Dynamic Range
- High Efficiency
- Standard RSOA Chip on Carrier
- Cost Effective

Application

- Optical Communications
- LiDAR
- Free Space Communications
- Network Test Equipment



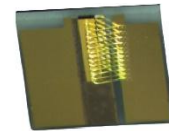
SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary, we will further optimize the design of our InP & GaSb laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.

High Power RSOA Chip on Carriers



Specification

COC-286



Optical	Symbol	Typ.	Units
Center Wavelength	λ_c	1550	nm
ASE Output Power @ 1A	P _{out}	0.2	watts
Aperture Width	AW	4	μm
Spectral Width	$\Delta\lambda$	85	nm @ 3dB
Beam Exit Angle	θ_{EXT}	19.5	Degree
Fast Axis Div.	θ_{\perp}	30	Deg FWHM
Slow Axis Div.	θ_{\parallel}	20	Deg FWHM
Front Facet Reflectivity		<0.1%	
Rear Face Reflectivity		98%	
Waveguide		Curved	
Electrical	Symbol		Units
Operating Current	I _{op}	1	A
Operating Voltage	V _{op}	2	V
Mechanical		Range	Units
Chip Width		500	μm
Operating Temp.**		-20 to 75	°C
Storage Temp.		-40 to 85	°C

*Specified values are rated at a constant heat sink temperature of 20°C.

**High temperature operation will reduce performance and MTTF.
Unless otherwise indicated all values are nominal.

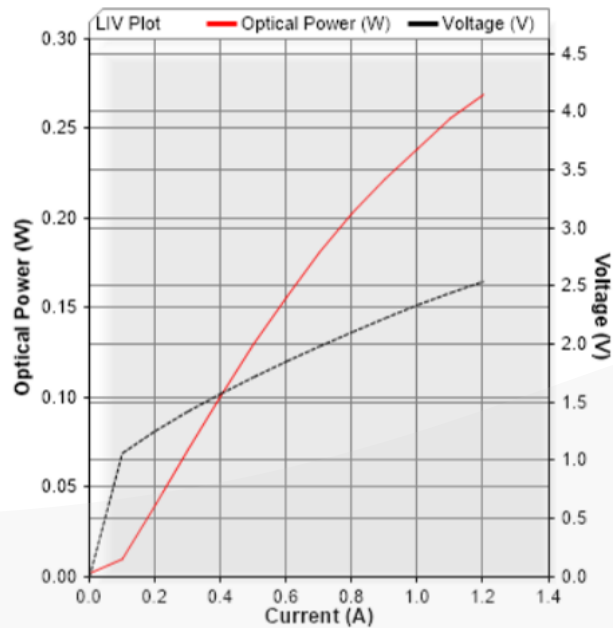
High Power RSOA Chip on Carriers



SemiNex RSOA COC-286

Graphs & Data

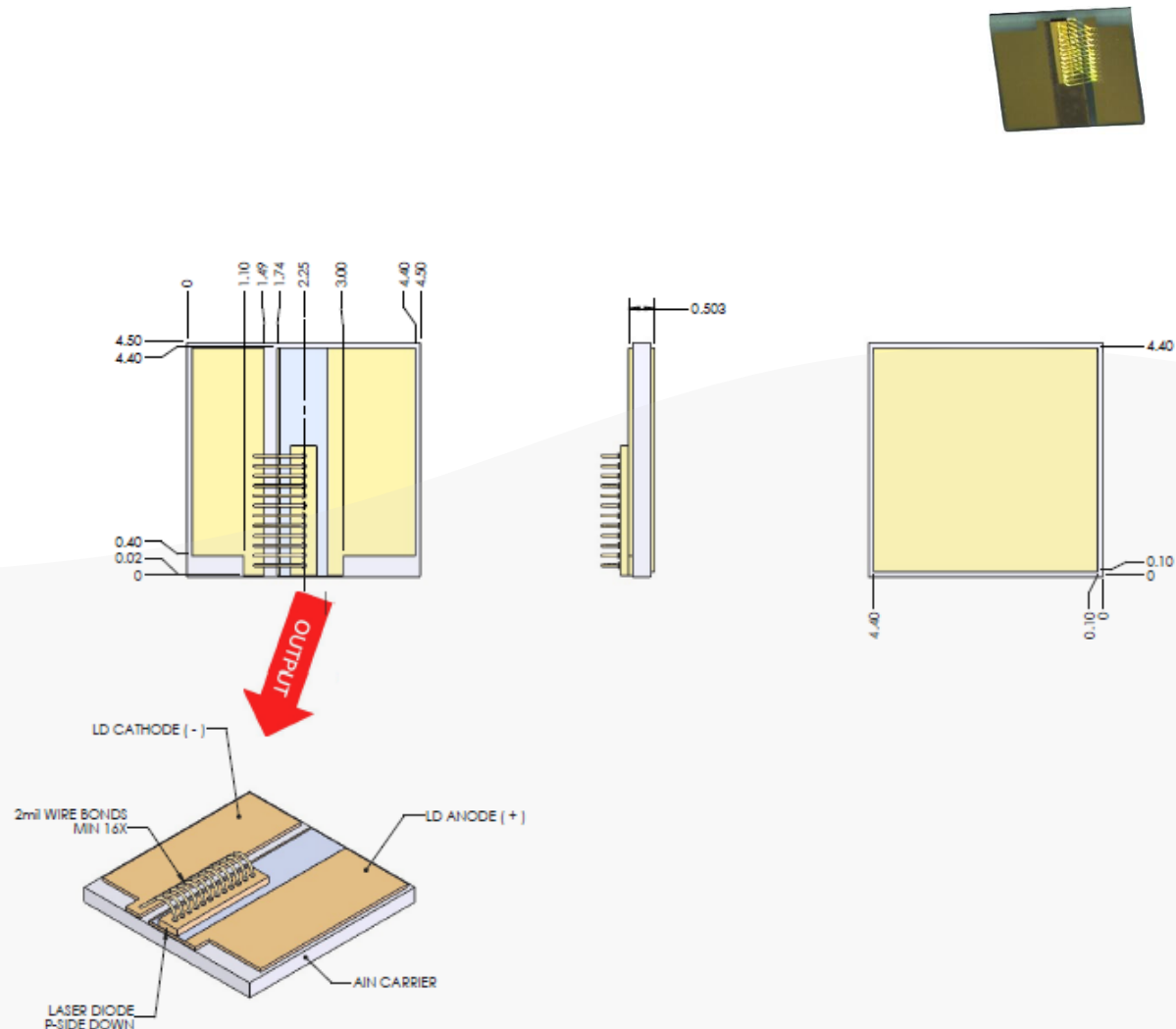
Typical ASE L-I-V Characteristics



High Power RSOA Chip on Carriers



Mechanical Drawing



All statements, technical information and recommendations related to the product herein are based upon information believed to be reliable or accurate. The accuracy or completeness herein is not guaranteed, and no responsibility is assumed for any inaccuracies. The user assumes all risks and liability whatsoever in connection with the use of a product or its application. SemiNex Corporation reserves the right to change at any time without notice the design, specification, deduction, fit or form of its described herein, including withdrawal at any time of a product offered for sale herein. Users are encouraged to visit www.seminex.com for the latest data. SemiNex Corporation makes no representations that the products herein are free from any intellectual property claims of others. Please contact SemiNex for more information. 2016 SemiNex Corporation

